



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS4160DGA		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000990172							
<b>Package</b>		PG-DSO-14-37		<b>Weight*</b>		144.23 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.505	2.43	2.43	24299	24299	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105		
	non noble metal	zinc	7440-66-6	0.060	0.04		418		
	non noble metal	iron	7439-89-6	1.207	0.84		8368		
wire	non noble metal	copper	7440-50-8	49.007	33.98	34.87	339780	348671	
	noble metal	gold	7440-57-5	1.489	1.03	1.03	10326	10326	
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1188	
plastics		epoxy resin	-	7.882	5.46		54648		
	inorganic material	silicondioxide	60676-86-0	77.620	53.83	59.41	538166	594002	
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8501	8501	
plating	noble metal	silver	7440-22-4	1.030	0.71	0.71	7140	7140	
glue	plastics	epoxy resin	-	0.178	0.12		1236		
	noble metal	silver	7440-22-4	0.840	0.58	0.70	5825	7061	
*deviation	< 10%				Sum in total:		100,00		1000000

### Important Remarks:

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